



PK130 (v1.3) November 18, 2011

100% Material Declaration Data Sheet for VQG100 Package

Average Weight: 0.5392 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.017360	3.220
	Silicon (Si)	7440-21-3	100.00		0.017360	
Die Attach					0.025760	4.778
	Silver (Ag)	7440-22-4	72.00		0.018547	
	Epoxy (EP)	254-641-8	7.00		0.001803	
	Aliphatic acid anhydride	Trade Secret	7.00		0.001803	
	2,6-Diglycidyl phenyl allyl ether oligomer	417-470-1	5.00		0.001288	
	Epoxy derivative	Trade Secret	3.00		0.000773	
	Hexahydro-4-methylphthalic anhydride	243-072-0	3.00		0.000773	
	1,4-bis(2,3-epoxypropoxy)butane	219-371-7	3.00		0.000773	
Mold Compound					0.347130	64.382
	Epoxy Resin	Trade secret	7.00		0.024299	
	Phenol Resin	Trade secret	5.00		0.017357	
	Carbon Black	1333-86-4	0.30		0.001041	
	Fused Silica	60676-86-0	87.70		0.304433	
Leadframe					0.140910	26.135
	Copper (Cu)	7440-50-8	98.28		0.138486	
	Chromium (Cr)	7440-47-3	0.25		0.000352	
	Tin (Sn)	7440-31-5	0.25		0.000352	
	Zinc (Zn)	7440-66-6	0.22		0.000310	
	Silver (Ag)	7440-22-4	1.00		0.001409	
Solder Plating					0.005910	1.096
	Tin (Sn)	7440-31-5	100.00		0.005910	
Gold Wire					0.002100	0.389
	Gold (Au)	7440-57-5	99.00		0.002079	
	Palladium	7440-05-3	1.00		0.000021	

© Copyright 2011 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/20/06	1.0	Initial Xilinx release.
07/05/06	1.1	100% Material Declaration
10/05/06	1.2	Corrected component descriptions
11/18/11	1.3	Updated component weights and descriptions

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.